

Title (en)

Electroless copper plating bath and plating method using such bath.

Title (de)

Bad und Lösung zum stromlosen Verkupfern.

Title (fr)

Bain et procédé pour le cuivrage chimique.

Publication

EP 0164580 A2 19851218 (EN)

Application

EP 85105723 A 19850510

Priority

US 61127884 A 19840517

Abstract (en)

The electroless copper plating bath having improved stability contains a cationic polymer from acrylamide and/or methacrylamide. The plating bath also contains essentially a cupric ion source, a reducing agent for the cupric ion source, and a complexing agent for the cupric ion. A substrate to be plated is contacted with the plating bath maintained preferably at a temperature in the range between about 70 DEG C and about 80 DEG C.

IPC 1-7

C23C 18/40

IPC 8 full level

C23C 18/40 (2006.01)

CPC (source: EP)

C23C 18/40 (2013.01)

Cited by

US4834796A; EP0221265A1; AU579776B2; CN100462480C; US4814009A; US5039338A; US5965211A; EP1681371B1

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